



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: James C. Matayabas et al.

Title: POLYMER SOLDER HYBRID INTERFACE MATERIAL WITH IMPROVED SOLDER FILLER PARTICLE SIZE AND MICROELECTRONIC PACKAGE APPLICATION

Docket No.: 884.946US1
Filed: June 30, 2003
Examiner: Howard Weiss

Serial No.: 10/612,328
Due Date: October 14, 2005
Group Art Unit: 2814

MS Amendment

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

- ☒ Return postcard.
- ☒ Amendment and Response (6 pgs.).

Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
Customer Number 21186

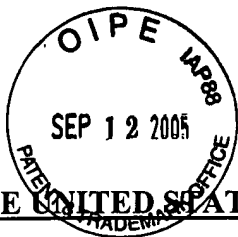
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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 8th day of September, 2005.

Amy Moriarty
Name

[Signature]
Signature

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
(GENERAL)



S/N 10/612,328

PATENT

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Title: POLYMER SOLDER HYBRID INTERFACE
MATERIAL WITH IMPROVED SOLDER FILLER
PARTICLE SIZE AND MICROELECTRONIC
PACKAGE APPLICATION

Assignee: Intel Corporation

Customer Number: 21186

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

MS Amendment
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This responds to the Office Action mailed on July 14, 2005. Please amend the above-identified patent application as follows.